



KYI-H800 series (Thermal Gap Filler)

DATA SHEET



- Product picture -

FEATURES:

- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions; Unqualified for storage conditions: 6 months.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Gray	-	Visual
Thickness	0.5~3	mm	ASTM D 374
Hardness	35(± 5)	Shore C	ASTM D 2240
Density	3.4(± 0.3)	g/cc	ASTM D 792
Tensile Strength	≥ 0.12	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 20 (@50Psi)	%	ASTM D 695
Tear strength	≥ 0.35	N/mm	ASTM D 624
UL Certification	V-0	-	UL 94
Operating Temperature	-40~130	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	8.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.2 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 3	KV/mm	ASTM D 149
Volume Resistivity	$\geq 10^{10}$	$\Omega\cdot\text{cm}$	ASTM D 257
Dielectric constant	≥ 5	@1MHz	ASTM D 150
Dielectric loss	≤ 0.1	@1MHz	ASTM D 150